



**Ordering Information:**

**Absolute Maximum Ratings**  $T_C = 25$

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_{D@T_C=25}$	60	A
	$I_{D@T_C=75}$		



Single Pulse Avalanche Energy ( $L=0.1\text{mH}, V_{GS}=10\text{V}, R_g=25\ \Omega, t_J=25\ \mu\text{s}$ )	$E_{AS}$	66	mJ
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**Thermal resistance**

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	$R_{thJC}$	-	-	1.5	$^{\circ}\text{C/W}$
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	37	$^{\circ}\text{C/W}$
Soldering temperature, wave soldering for 10s	$T_{sold}$	-	-	265	$^{\circ}\text{C}$

**Electronic Characteristics**

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	40			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}, I_D=250\mu\text{A}$	1.2		2.5	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=40\text{V}, V_{GS}=0\text{V}$			1.0	$\mu\text{A}$
Gate- Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20\text{V},$				



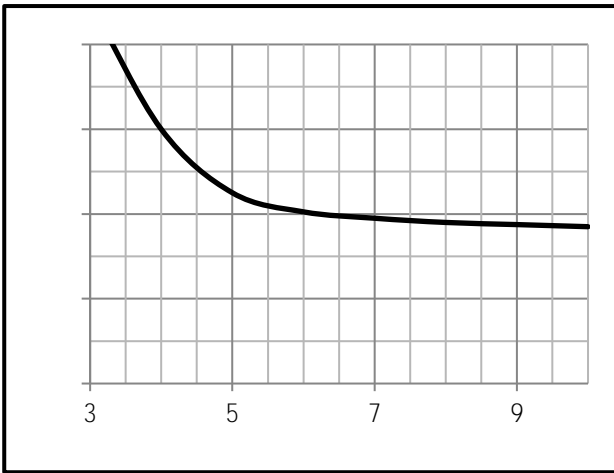


Fig.7 SOA Maximum Safe Operating Area

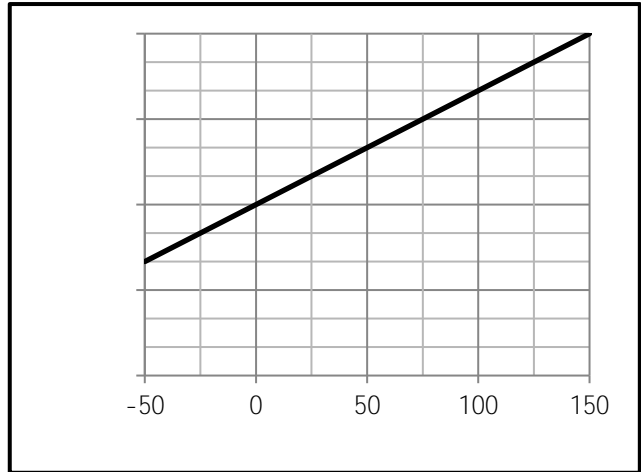
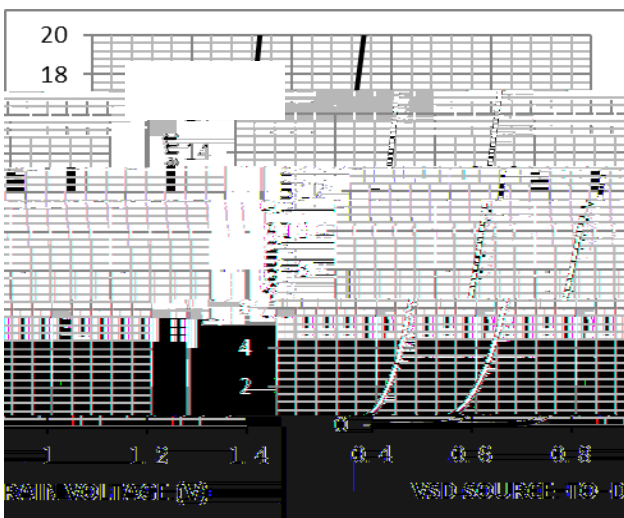
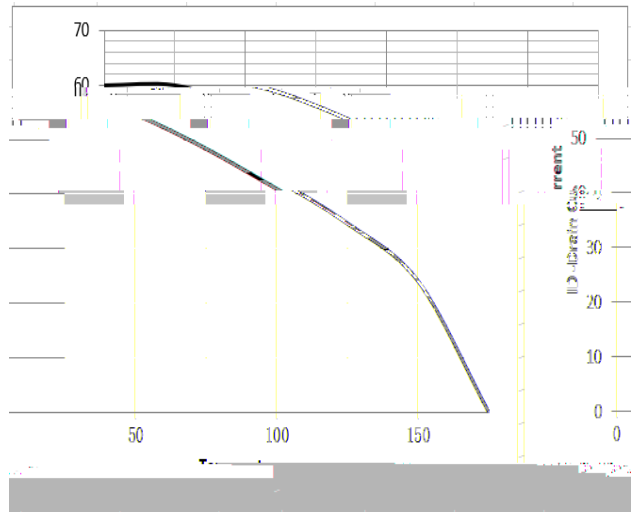


Fig.8 ID-Junction Temperature









Dimensions DFN5x6

Unit mm

